

High Power Laser Diode Chip



Part Number: CHP-107

High Power Chip
Multi-Mode Fabry-Perot
CW Wavelength at 1470nm



Features

- High Output Power
- High Dynamic Range
- High Efficiency
- Standard Bare Die
- Cost Effective

Application

- Professional Medical



SemiNex delivers the highest available power at infrared wavelengths between 12xx and 19xx nm. When necessary, we will further optimize the design of our InP & GaSb laser chips to meet our customers' specific optical and electrical performance needs. Diodes, bars and packages are tested to meet customer and market performance demands. Typical results and packaging options are shown. Contact SemiNex for additional details or to discuss your specific requirements.

High Power Laser Diode Chip



Specification

CHP-107



Optical	Symbol	Typ.	Units
Center Wavelength	λ_c	1470	nm (± 20)
Output Power (CW)*	P_{out}	7	watts ($\pm 10\%$)
Chip Cavity Length	CL	2500	μm
Emitter Width	W	180	μm
Spectral Width FWHM	$\Delta\lambda$	15	nm
Slope Efficiency	η	0.37	W/A
Fast Axis Div.	θ_{\perp}	28	deg FWHM
Slow Axis Div.	θ_{\parallel}	9	deg FWHM
Electrical	Symbol		Units
Power Conversion Eff.	η	21	%
Threshold Current	I_{TH}	0.5	A
Operating Current	I_{op}	21	A
Operating Voltage	V_{op}	1.7	V
Mechanical		Range	Units
Operating Temp.**		-40 to 60	$^{\circ}\text{C}$
Storage Temp.		-40 to 80	$^{\circ}\text{C}$

*Specified values are rated at a constant heat sink temperature of 20°C.

**High temperature operation will reduce performance and MTTF.
Unless otherwise indicated all values are nominal.

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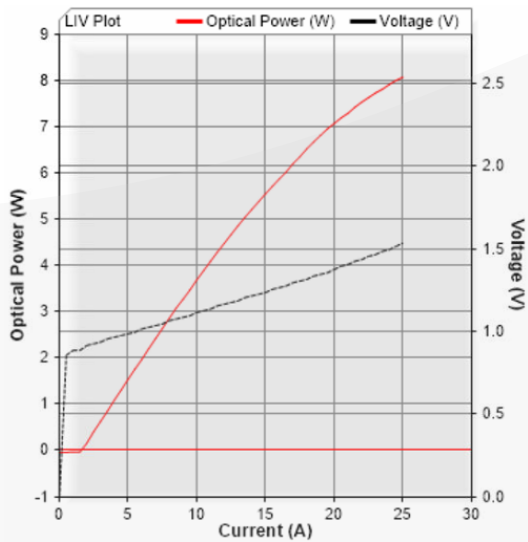


SemiNex Laser Diodes CHP-107

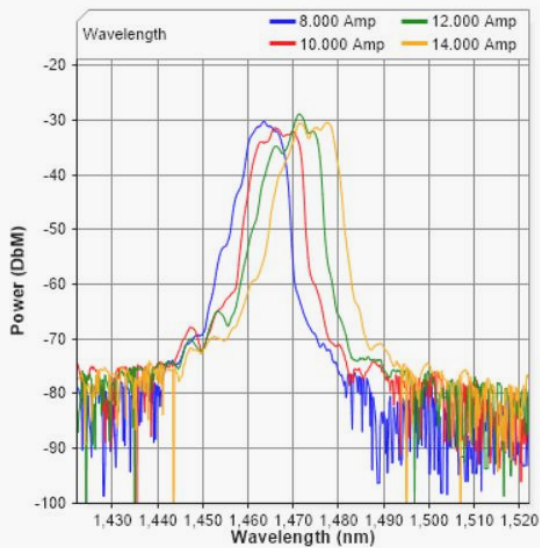
Graphs & Data



Typical CHP L-I-V Characteristics



Typical CHP Output Spectrum



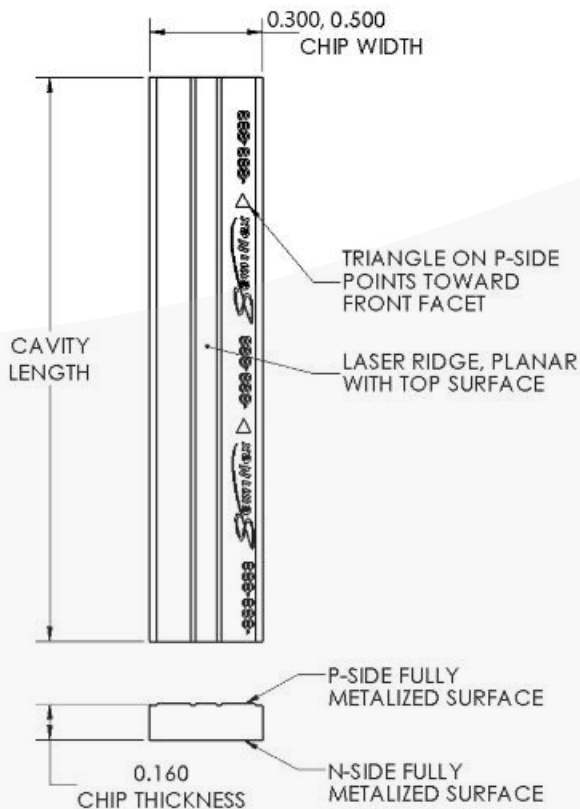
*Graphs and Data were collected from mounted parts

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Mechanical Drawing



CHIP ATTRIBUTES

APERTURE WIDTH (μm)	Single Mode (4, 5) ± 1 Multi Mode (50, 95, 180, 350) ± 3
CHIP WIDTH (μm)	300, 500 ± 10
THICKNESS (μm)	160 ± 10
CAVITY LENGTH (μm)	Varies ± 10

P METALIZATION

MATERIAL	THICKNESS (nm)	TOLERANCE (nm)
Ti	50	± 10
Pt	125	± 25
Au	250	± 50

N METALIZATION

MATERIAL	THICKNESS (nm)	TOLERANCE (nm)
Ti	30	± 10
Pt	125	± 25
Au	400	± 40

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